

MODULE WITH ADHESIVELY ATTACHED HEAT SINK

Abstract of the Disclosure

A method and structure to adhesively couple a cover plate to a semiconductor device. A semiconductor device is electrically coupled to a substrate. A stiffener ring surrounding the semiconductor device is adhesively coupled to the substrate. A cover plate is adhesively coupled to both a top surface of the semiconductor device and a top surface of the stiffener ring using a first and second adhesive, respectively. The modulus of the first adhesive is less than the modulus of the second adhesive.